LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L
337 ZWT LAUNCHPAD XL2

POWER/USB JACKS
SHEET 17

VOLTAGE REGULATOR
SHEET 11
+5V
+3.3V
+1.2V

XDS110 DEBUG PROBE
SHEETS 15, 16

SENSOR & SWITCHES
SHEET 10

HERCULES TMS570LC4357/RM57L843 MCU
SHEETS 2, 3, 4, 5, 6

BOOSTER PACK IOS (1ST SET)
SHEET 7
BOOSTER PACK IOS (SECOND SET)
SHEET 8

USER LEDS
SHEET 10

DP83630 PRECISION PHYTER
SHEET 12

RJ-45 + MAGNETICS
SHEET 12

PROTO BOARD HEADERS
SHEET 9

MEZZANINE HEADERS
SHEETS 13, 14

BOOSTER PACK SITE #1

BOOTER PACK SITE #2

VOLTAGE REGULATOR
SHEET 11

ADDITIONAL PERIPHERAL IO

EMIF
RTP/DMM
ETM
JTAG
+ PERIPHERALS

GIO

MDI
LEDS

N2HET (time sync)

MDIO

MII (or RMII)

JTAG

GIO

JTAG

ETM

RTP/DMM

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SHEETS 13, 14
CAUTION:
BEFORE POPULATING R4, REMOVE R3!
U1E
RMS7L843_TMS5570LC4357_ZWT_337

TITLE: LAUNCHXL2_570LC43_RM57L
Document Number: LAUNCHXL2-570LC43 / LAUNCHXL2-RM57L
REV: A1
Date: 5/19/2015 7:09 PM Sheet: 6/17
NOTES:

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JP2 & JP3 are normally shorted on the PCB - the footprint consists of an (unpopulated) 2 pin SMT header and a solder-bridging structure. Most users can leave these jumpers as-is.

Certain booster packs may require that the position is opened - these are booster packs that would otherwise supply power to the launchpad through these pins. Providing +3V3 to the launchpad is a problem because there would be a conflict with the launchpad's on-board LM26420 regulator. Providing +5V to the launchpad through the booster pack could be ok, but the barrel jack is preferred as it is protected with a PTC. Also be careful to avoid back powering the USB connection if you do this.

In some cases you may find the need to make/break the connections JP2,JP3 frequently. If you do, then you can remove the solder bridge and mount a 2 pin SMT header on the footprint location which can then be opened/closed by using a Jumper or Shunt.

Headers/Receptacles may be ordered from http://launchpad.mlelectronics.com/
NOTES:

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JP4 & JP5 are normally shorted on the PCB - the footprint consists of an (unpopulated) 2 pin SMT header and a solder-bridging structure. Most users can leave these jumpers as-is.

Certain booster packs may require that the position is opened - these are booster packs that would otherwise supply power to the launchpad through these pins. Providing +3V3 to the launchpad is a problem because there would be a conflict with the launchpad's on-board LM26420 regulator. Providing +5V to the launchpad through the booster pack could be ok, but the barrel jack is preferred as it is protected with a PTC. Also be careful to avoid back powering the USB connection if you do this.

In some cases you may find the need to make/break the connections JP4, JP5 frequently. If you do, then you can remove the solder bridge and mount a 2 pin SMT header on the footprint location which can then be opened/closed by using a Jumper or Shunt.

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TRIM POT. FOR ANALOG INPUT
(REPLACES TEMP SENSOR)
HERCULES POWER

POWER INDICATOR LED

+5V
**PHYS ADDRESS**

**PHYADDR[4:0] = 00001b**

MCU & PHY Pulls Match

PHYAD0 (COL) = PU

PHYAD1 (RXDD) = PD

PHYAD2 (RXD2) = PD

PHYAD3 (RXD3) = PD

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